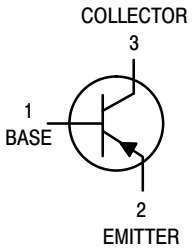
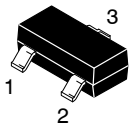
# General Purpose Transistors

## PNP Silicon

# BC808-25LT1G, BC808-40LT1G




**SOT−23**
**CASE 318**
**STYLE 6**

### Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

### MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|---|---|---|
| Collector − Emitter Voltage | $V_{CEO}$ | −25 | V |
| Collector − Base Voltage | $V_{CBO}$ | −30 | V |
| Emitter − Base Voltage | $V_{EBO}$ | −5.0 | V |
| Collector Current − Continuous | $I_C$ | −500 | mAdc |

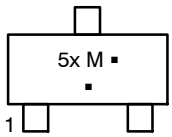
### THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|---|---|---|---|
| Total Device Dissipation FR−5 Board, (Note 1) $T_A$ = 25°C<br>Derate above 25°C | $P_D$ | 225<br>1.8 | mW<br>mW/°C |
| Thermal Resistance, Junction−to−Ambient | $R_{\theta JA}$ | 556 | °C/W |
| Total Device Dissipation Alumina Substrate, (Note 2) $T_A$ = 25°C<br>Derate above 25°C | $P_D$ | 300<br>2.4 | mW<br>mW/°C |
| Thermal Resistance, Junction−to−Ambient | $R_{\theta JA}$ | 417 | °C/W |
| Junction and Storage Temperature | $T_J$, $T_{stg}$ | −55 to +150 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR−5 = 1.0 x 0.75 x 0.062 in.
2. Alumina = 0.4 x 0.3 x 0.024 in 99.5% alumina.

### MARKING DIAGRAM




5x = Device Code
x = F or G
M = Date Code*
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 2.

**ELECTRICAL CHARACTERISTICS** ($T_A$ = 25°C unless otherwise noted.)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| **OFF CHARACTERISTICS** | | | | | |
| Collector − Emitter Breakdown Voltage ($I_C$ = −10 mA) | $V_{(BR)CEO}$ | −25 | − | − | V |
| Collector − Emitter Breakdown Voltage ($V_{EB}$ = 0, $I_C$ = −10 μA) | $V_{(BR)CES}$ | −30 | − | − | V |
| Emitter − Base Breakdown Voltage ($I_E$ = −1.0 μA) | $V_{(BR)EBO}$ | −5.0 | − | − | V |
| Collector Cutoff Current ($V_{CB}$ = −20 V) ($V_{CB}$ = −20 V, $T_J$ = 150°C) | $I_{CBO}$ | <br>− <br>− | <br>− <br>− | <br>−100 <br>−5.0 | <br>nA <br>μA |
| **ON CHARACTERISTICS** | | | | | |
| DC Current Gain ($I_C$ = −100 mA, $V_{CE}$ = −1.0 V) BC808−25LT1G BC808−40LT1G ($I_C$ = −500 mA, $V_{CE}$ = −1.0 V) | $h_{FE}$ | <br>160 <br>250 <br>40 | <br>− <br>− <br>− | <br>400 <br>600 <br>− | − |
| Collector − Emitter Saturation Voltage ($I_C$ = −500 mA, $I_B$ = −50 mA) | $V_{CE(sat)}$ | − | − | −0.7 | V |
| Base − Emitter On Voltage ($I_C$ = −500 mA, $I_B$ = −1.0 V) | $V_{BE(on)}$ | − | − | −1.2 | V |
| **SMALL−SIGNAL CHARACTERISTICS** | | | | | |
| Current − Gain − Bandwidth Product ($I_C$ = −10 mA, $V_{CE}$ = −5.0 Vdc, f = 100 MHz) | $f_T$ | 100 | − | − | MHz |
| Output Capacitance ($V_{CB}$ = −10 V, f = 1.0 MHz) | $C_{obo}$ | − | 10 | − | pF |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## ORDERING INFORMATION

| Device | Specific Marking | Package | Shipping† |
|---|---|---|---|
| BC808−25LT1G | 5F | SOT−23 (Pb−Free) | 3000 / Tape & Reel |
| SBC808−25LT1G | | | |

**DISCONTINUED** (Note 3)

| | | | |
|---|---|---|---|
| BC808−40LT1G | 5G | SOT−23 (Pb−Free) | 3000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

3. **DISCONTINUED:** This device is not recommended for new design. Please contact your **onsemi** representative for information. The most current information on this device may be available on www.onsemi.com.

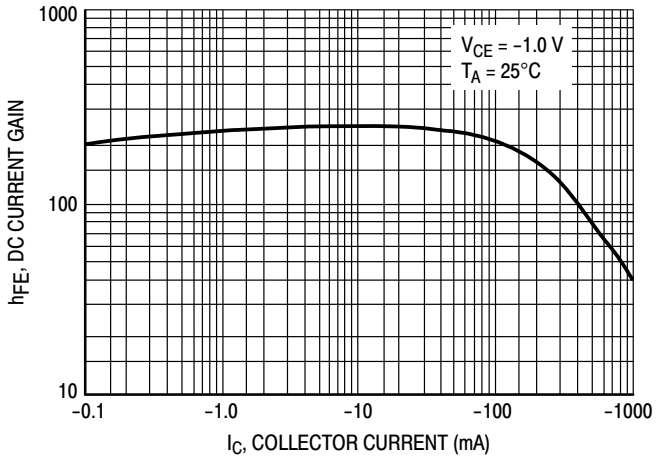



**Figure 1. DC Current Gain**

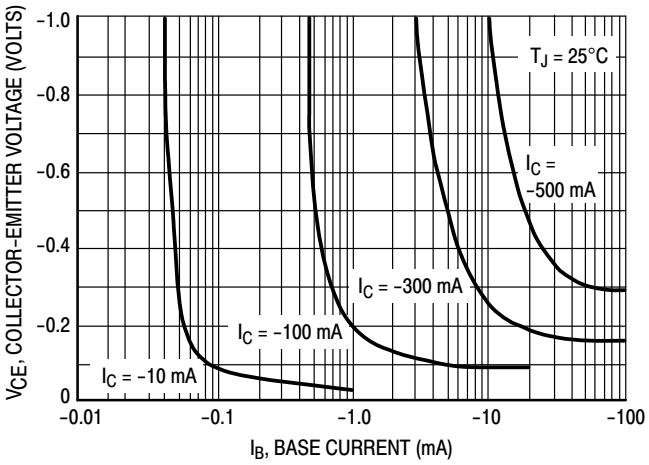



**Figure 2. Saturation Region**

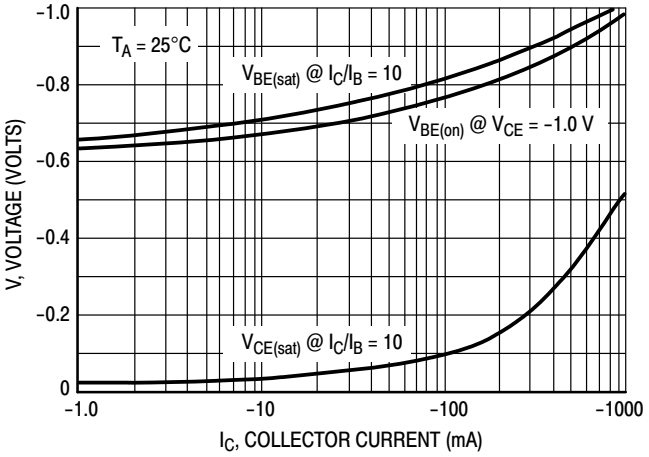



**Figure 3. “On” Voltages**

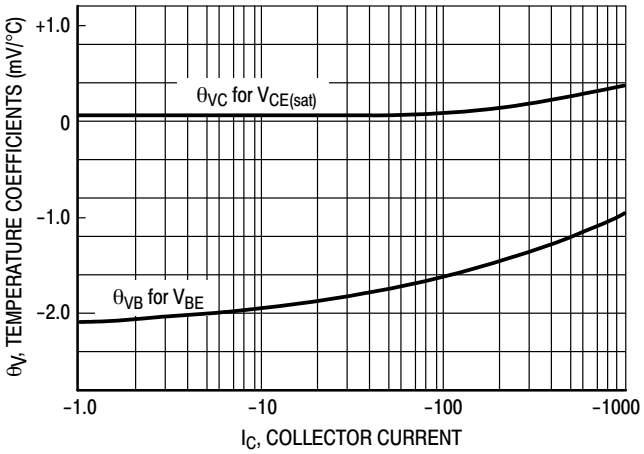



**Figure 4. Temperature Coefficients**

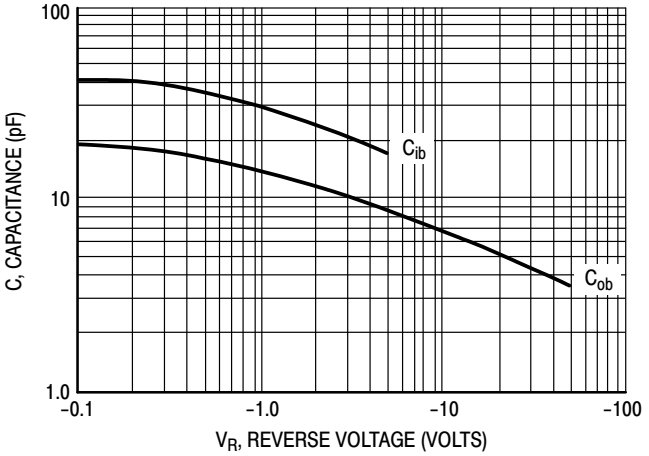
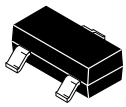


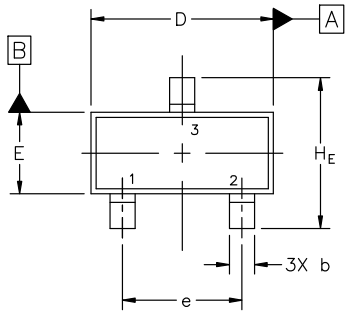

**Figure 5. Capacitances**



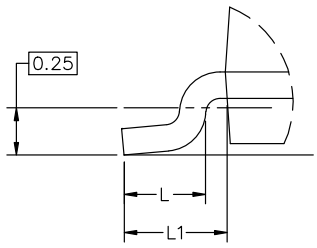
**SCALE 4:1**

**SOT−23 (TO−236) 2.90x1.30x1.00 1.90P**
CASE 318
ISSUE AU

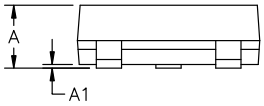
DATE 14 AUG 2024



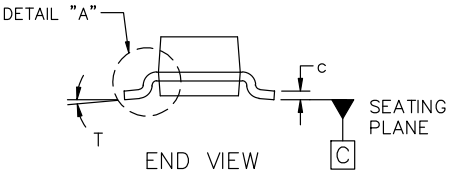

TOP VIEW




DETAIL "A"
Scale 3:1




SIDE VIEW

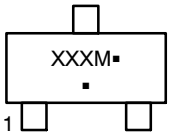



END VIEW

| MILLIMETERS | | | |
|---|---|---|---|
| DIM | MIN | NOM | MAX |
| A | 0.89 | 1.00 | 1.11 |
| A1 | 0.01 | 0.06 | 0.10 |
| b | 0.37 | 0.44 | 0.50 |
| c | 0.08 | 0.14 | 0.20 |
| D | 2.80 | 2.90 | 3.04 |
| E | 1.20 | 1.30 | 1.40 |
| e | 1.78 | 1.90 | 2.04 |
| L | 0.30 | 0.43 | 0.55 |
| L1 | 0.35 | 0.54 | 0.69 |
| $H_E$ | 2.10 | 2.40 | 2.64 |
| T | 0° | −−− | 10° |

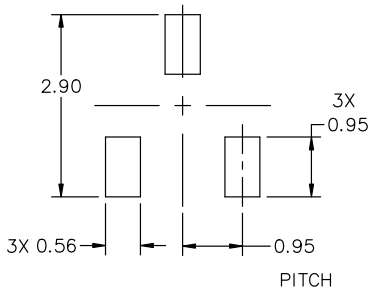
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

**GENERIC**
**MARKING DIAGRAM***




XXX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.




RECOMMENDED
MOUNTING FOOTPRINT

* For additional information on our Pb−Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**STYLES ON PAGE 2**

| | | | |
|---|---|---|---|
| **DOCUMENT NUMBER:** | **98ASB42226B** | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. | |
| **DESCRIPTION:** | **SOT−23 (TO−236) 2.90x1.30x1.00 1.90P** | | **PAGE 1 OF 2** |

**SOT−23 (TO−236) 2.90x1.30x1.00 1.90P**
CASE 318
ISSUE AU

DATE 14 AUG 2024

STYLE 1 THRU 5:
CANCELLED

STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

STYLE 7:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

STYLE 8:
PIN 1. ANODE
2. NO CONNECTION
3. CATHODE

STYLE 9:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 10:
PIN 1. DRAIN
2. SOURCE
3. GATE

STYLE 11:
PIN 1. ANODE
2. CATHODE
3. CATHODE−ANODE

STYLE 12:
PIN 1. CATHODE
2. CATHODE
3. ANODE

STYLE 13:
PIN 1. SOURCE
2. DRAIN
3. GATE

STYLE 14:
PIN 1. CATHODE
2. GATE
3. ANODE

STYLE 15:
PIN 1. GATE
2. CATHODE
3. ANODE

STYLE 16:
PIN 1. ANODE
2. CATHODE
3. CATHODE

STYLE 17:
PIN 1. NO CONNECTION
2. ANODE
3. CATHODE

STYLE 18:
PIN 1. NO CONNECTION
2. CATHODE
3. ANODE

STYLE 19:
PIN 1. CATHODE
2. ANODE
3. CATHODE−ANODE

STYLE 20:
PIN 1. CATHODE
2. ANODE
3. GATE

STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN

STYLE 22:
PIN 1. RETURN
2. OUTPUT
3. INPUT

STYLE 23:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 24:
PIN 1. GATE
2. DRAIN
3. SOURCE

STYLE 25:
PIN 1. ANODE
2. CATHODE
3. GATE

STYLE 26:
PIN 1. CATHODE
2. ANODE
3. NO CONNECTION

STYLE 27:
PIN 1. CATHODE
2. CATHODE
3. CATHODE

STYLE 28:
PIN 1. ANODE
2. ANODE
3. ANODE

## ADDITIONAL INFORMATION

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